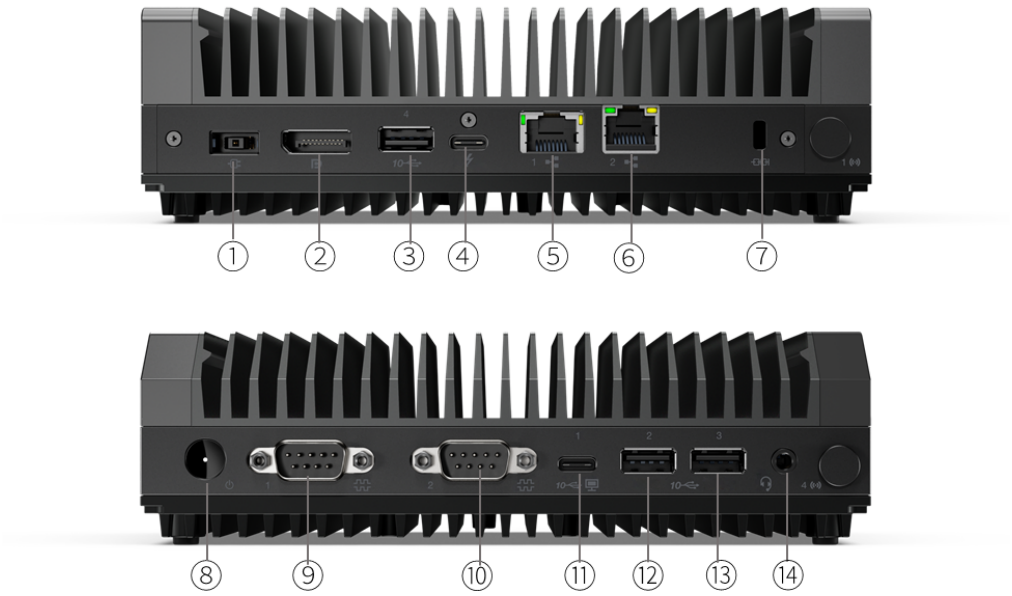
OVERVIEW



1. Power connector	8. Power button
2. HDMI (for Celeron, i3) / DisplayPort (for i5)	9. Serial
3. USB 3.2 Gen 2	10. Serial
4. Thunderbolt 4	11. USB-C 3.2 Gen 2
5. Ethernet (RJ-45)	12. USB 3.2 Gen 2
6. Ethernet (RJ-45)	13. USB 3.2 Gen 2
7. Kensington Security Slot	14. Headphone / microphone combo jack (3.5mm)

PERFORMANCE

Processor

Processor Family

Intel® Celeron® or 11th Generation Intel Core™ i3 / i5 Processor

Processor[**][1]

Processor Name	Cores	Threads	Base Frequency	Cache	Memory Support	Processor Graphics
Celeron 6305E[2]	2	2	1.8GHz	4MB	DDR4-3200	Intel UHD Graphics
Core i3-1115GRE[3]	2	4	1.7GHz	6MB	DDR4-3200	Intel UHD Graphics
Core i5-1145G7E[4]	4	8	1.5GHz	8MB	DDR4-3200	Intel Iris® Xe Graphics
Core i5-1145GRE[5]	4	8	1.1GHz	8MB	DDR4-3200	Intel Iris Xe Graphics

Notes:

[1] The Intel® Turbo Boost is disabled. The maximum Thermal Design Power (TDP) of microprocessor might be 12W, 15W, or 28W, which depends on different microprocessor series. The max frequency might not be obtainable at high work levels, so the microprocessor will adjust the frequency to obtain the maximum TDP allowed.
[2] The maximum Thermal Design Power (TDP) is 15W.
[3], [5] The maximum Thermal Design Power (TDP) is 12W.
[4] The maximum Thermal Design Power (TDP) is 28W.

Operating System

Operating System**

- Ubuntu Core 20.04[1]
- Ubuntu Core 22.04[2]
- Ubuntu Server 20.04[3]
- Ubuntu Server 22.04[4]
- Windows® 10 IoT Enterprise LTSC 2019[5]
- Windows 10 IoT Enterprise LTSC 2021
- No operating system

Notes:

[1], [3], [5] For 11NA, 11NB, 11NC, 11NJ models
[2], [4] For 11NK, 11NH models

Graphics

Graphics**

Graphics	Type	Memory	Connector	Max Resolution	Key Features
Intel UHD graphics	Integrated	Shared	1x HDMI® 1.4b, 1x USB-C®, 1x Thunderbolt™	3840x2160@30Hz(HDMI), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX® 12
Intel Iris Xe Graphics	Integrated	Shared	1x DP 1.4a, 1x USB-C, 1x Thunderbolt	3840x2160@60Hz(DP), 3840x2160@60Hz(USB-C), 3840x2160@60Hz(Thunderbolt)	DirectX 12

Monitor Support

Monitor Support

Supports up to 3 independent displays via onboard ports (Celeron, i3 models supports HDMI, USB-C, and Thunderbolt; i5 models supports DisplayPort™, USB-C, and Thunderbolt)

Chipset

Chipset

Intel SoC (System on Chip) platform

Memory

Max Memory

Up to 16GB soldered memory, not upgradable

Memory Slots

Memory soldered to systemboard, no slots, dual-channel

Memory Type

DDR4-3200

Memory Protection[1]

IB-ECC[2]

Notes:

[1] IB-ECC needs to be enabled in BIOS.
[2] For 11NA, 11NB, 11NC, 11NJ models only

Storage

Storage Support[1]

Up to two drives, 2x M.2 SSD
• M.2 2280 SSD up to 2TB each
• M.2 2230 SSD up to 1TB each
• RAID 0/1 support

Storage Type***

Disk Type	Interface	Security
M.2 2230 SSD	PCIe® NVMe®, PCIe 3.0	-
M.2 2230 SSD	PCIe NVMe, PCIe 3.0	Opal
M.2 2280 SSD[2]	PCIe NVMe, PCIe 4.0 x4	Opal 2.0
M.2 2280 SSD	PCIe NVMe, PCIe 4.0 x4 Performance	Opal 2.0

RAID[3]

RAID 0/1 support

Notes:

[1] M.2 2280 SSD is for 11NK, 11NH models.
M.2 2230 SSD is for 11NA, 11NB, 11NC, 11NJ models.
[2] For 11NK, 11NH models, M.2 PCIe Gen 4 SSD in a M.2 PCIe Gen 3 slot runs at PCIe Gen 3 speeds.
[3] RAID preset is available via special bid, limited to the models with Windows 10 IoT Enterprise.

Power Supply

Power Supply**

Power	Type	Efficiency	Key Features	Dimensions
65W	Adapter	89%	100-240V	129 x 53 x 30 mm, 1800 mm cable
65W	Adapter	88%	100-240V, for SE30 (11NK, 11NH)	108 x 46 x 29 mm, 1800 mm cable
No power supply	-	-	-	-

DESIGN

Input Device

Keyboard**

- Lenovo® Calliope Keyboard (USB connector), black
- Lenovo Calliope Wireless Keyboard, black
- Lenovo Traditional Keyboard (USB connector), black
- No keyboard

Mouse**

- Lenovo Calliope Mouse (USB connector), black
- Lenovo Fingerprint Mouse (USB connector), black (EOL on Jan, 2023)
- No mouse

Mechanical

Dimensions (WxDxH)[1]

Models	Dimensions
IO box	178 x 88 x 25.6 mm (7.01 x 3.46 x 1.00 inches)
ThinkEdge SE30	179 x 88 x 51.5 mm (7.05 x 3.46 x 2.03 inches)

Packaging Dimensions (WxDxH)

- SE 30 (Mini package): 245 x 113 x 258 mm (9.65 x 4.45 x 10.16 inches)
- SE 30 (Standard package): 491 x 153 x 264 mm (19.33 x 6.02 x 10.39 inches)

Weight[2]

Models	Weight
IO box	Around 0.499 kg (1.10 lbs)
ThinkEdge SE30	Around 1.02 kg (2.25 lbs)

Packaging Weight[3]

- SE 30 (Mini package): Around 1.65 kg (3.63 lbs)
- SE 30 (Standard package): Strat at 4.11 kg (9.06 lbs)

Case Color

Black

IO Box[4]

- ThinkEdge SE30 IO box: 2x serial (RS232 / RS422 / RS485) and 2x gigabit Ethernet (RJ-45) on front, 1x DIO (4DI / 4DO), USB-C 3.2 Gen 1 (connect to SE30), and DC-in connector (9V - 36V) on rear
- No IO box

Mounting**

- VESA mount bracket kit with adapter holder, supports VESA mount 75mm and 100mm
- VESA mount bracket kit, supports VESA mount 75mm and 100mm
- DIN rail mount bracket kit
- Z hook
- None

Notes:

[1] The system dimensions may vary depending on configurations.

[2] The system weight is approximate and based on results in Lenovo lab, which varies depending on the source of component, variance of the distribution of each component, and manufacturing process. It may not be the exact weight for each specific model.

[3] The packaging weight is varies depending on the selected accessories.

[4] For more details, please go to https://pcsupport.lenovo.com.

CONNECTIVITY

Network

Ethernet

- Gigabit Ethernet (Realtek® RTL8111KI) and 2.5 Gigabit Ethernet (Intel I225-V), 2x RJ-45, supports Wake-on-LAN[1]
- Gigabit Ethernet (Realtek RTL8111KI) and 2.5 Gigabit Ethernet (Intel I225-LM), 2x RJ-45, supports Wake-on-LAN[2]
- Gigabit Ethernet (Realtek RTL8111KI) and 2.5 Gigabit Ethernet (Intel I225-IT), 2x RJ-45, supports Wake-on-LAN[3]

WLAN + Bluetooth®**[4]

- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi® + Bluetooth 5.1, M.2 card
- Intel Wireless-AC 9260, 802.11ac Dual Band 2x2 Wi-Fi + Bluetooth 5.1, Intel vPro® technology support, M.2 card
- Intel Wi-Fi 6 AX201, 802.11ax 2x2 Wi-Fi + Bluetooth 5.1, Intel vPro technology support, M.2 Card
- Intel Wi-Fi 6 AX201, 802.11ax 2x2 Wi-Fi + Bluetooth 5.1, M.2 Card
- No WLAN and Bluetooth

WWAN**[5]

- Qualcomm® Snapdragon™ X24, 4G LTE CAT16, M.2 card
- Qualcomm Snapdragon X55 5G Modem-RF System, Sub-6 GHz, M.2 card
- No support

Notes:

[1] For 11NK, 11NH Celeron models
[2] For 11NK, 11NH i5 models
[3] For 11NA, 11NB, 11NC, 11NJ models
[4] Bluetooth 5.1 is hardware ready but may run at a lower version due to OS limitations.
[5] WWAN cards for 11NA, 11NB, 11NC, 11NJ models only

Ports[1]

Front Ports

- 1x USB-C 3.2 Gen 2 (support data transfer and display)
- 2x USB 3.2 Gen 2
- 1x headphone / microphone combo jack (3.5mm)
- 2x serial (RS232 / RS422 / RS485, BIOS selectable)

Optional Front Ports***

- 2x gigabit Ethernet (RJ-45) on SE30 IO box
- 2x serial (RS232 / RS422 / RS485, SDK selectable) on SE30 IO box

Rear Ports[2]

- 1x Thunderbolt 4 / USB4® 40Gbps (support data transfer, Power Delivery 5V@3A and display)
- 1x USB 3.2 Gen 2
- 1x HDMI 1.4b (for Celeron, i3 models)
- 1x DisplayPort 1.4a (for i5 models)
- 1x power connector
- 2x Ethernet (RJ-45)

Optional Rear Ports***

- 1x USB-C 3.2 Gen 1 on SE30 IO box, connect to SE30
- 1x DC-in 3pin Phoenix connector on SE30 IO box
- 1x DIO (4DI / 4DO) on SE30 IO box

Notes:

[1] The transfer speed of following ports will vary and, depending on many factors, such as the processing speed of the host device, file attributes and other factors related to system configuration and your operating environment, will be slower than theoretical speed.
USB 2.0: 480 Mbit/s;
USB 3.2 Gen 1 (SuperSpeed USB 5Gbps, formerly USB 3.0 / USB 3.1 Gen 1): 5 Gbit/s;
USB 3.2 Gen 2 (SuperSpeed USB 10Gbps, formerly USB 3.1 Gen 2): 10 Gbit/s;
USB4 20Gbps / USB 3.2 Gen 2x2 (SuperSpeed USB 20Gbps): 20 Gbit/s;
USB4 40Gbps (USB 40Gbps): 40 Gbit/s;
Thunderbolt 3/4: 40 Gbit/s.
[2] If IO box gets power supply from ThinkEdge SE30, need to connect USB-C (on IO box) with Thunderbolt 4 port (on SE30).

Monitor Cable

Monitor Cable***

- USB-C to DP dongle
- USB-C to HDMI dongle
- USB-C to VGA dongle
- DP to VGA dongle
- DP to Dual DP (MST) dongle
- DP to Dual DP (SST) dongle
- DP to HDMI dongle
- No monitor cable

SECURITY & PRIVACY

Security

Security Chip

Discrete TPM 2.0, TCG certified

Physical Locks

Kensington® Security Slot™, 3 x 7 mm

Chassis Intrusion Switch

Chassis intrusion switch

BIOS Security

- Self-healing BIOS
- Self-healing BIOS (EC-based)

MANAGEABILITY

System Management

System Management

- Intel vPro with Intel AMT 15
- Non-vPro

SERVICE

Warranty[1]

Base Warranty**

- 1-year courier or carry-in service
- 1-year limited onsite service
- 3-year limited onsite service
- No base warranty

Notes:

[1] The warranty upgrades may be bundled with some models, please check the "Included upgrade" column in the specific model's configurations. For more service extensions, please go to https://smartfind.lenovo.com/. To learn more details of warranty policy, please access https://pcsupport.lenovo.com/warranty.

ENVIRONMENTAL

Operating Environment[1]

Temperature

- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -20°C (-4°F) to 60°C (140°F) with 0.7m/s air flow[2]
- Operating: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, 0°C (32°F) to 50°C (122°F) with 0.7m/s air flow[3]
- Storage: IEC60068-2-1 Test A: Cold, IEC 60068-2-2 Test B: Dry heat, -40°C (-40°F) to 85°C (185°F)

Humidity

- Relative humidity storage: IEC 60068-2-66 Damp heat, steady state 90%@60°C
- Relative humidity operating: IEC 60068-2-66 Damp heat, steady state 95%@40°C non-condensing

Shock Protection

IEC 60068-2-27, shock, operating, 30G / 11ms, half sine

Vibration Protection

IEC 60068-2-64, Vibration, Operating, 3Grms, random, 5 ~ 500Hz, 1hr/axis

Notes:

[1] The temperature spec is not applicable for hardware accessories.
[2] For 11NA, 11NB, 11NC, 11NJ models
[3] For 11NK, 11NH models

CERTIFICATIONS

Green Certifications[1]

Green Certifications

- ErP Lot 6/26
- Low Halogen
- PCF
- REACH
- RoHS compliant
- TED (ECO-declaration)
- WEEE

Notes:

[1] The items listed under the "Green Certifications" section may not only refer to certification but also registration or self-declaration.

Other Certifications

EMC

- EMC CE / FCC Class B
- BSMI
- CCC

Safety

- UL(ETL)
- BSMI
- CB
- CCC

- Feature with ** means that only one offering listed under the feature is configured on selected models.
- Feature with *** means that one or more offerings listed under the feature could be configured on selected models.
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